

L Number	Hits	Search Text	DB	Time stamp
13	1	6396699.pn.	USPAT;	2004/05/14 10:28
17	2	6437240.URPN.	US-PGPUB	2004/05/14 10:46
18	57	("2734154" "4034468" "4034469" "4233645" "4254431" "4299715" "4323914" "4398975" "4435611" "4466483" "4473113" "4607277" "4806111" "4915167" "4966142" "5011787" "5031308" "5037312" "5056706" "5071787" "5074947" "5086558" "5097387" "5131582" "5148141" "5148265" "5148266" "5164566" "5170930" "5196371" "5198189" "5223747" "5237130" "5323265" "5323294" "5328087" "5367435" "5410449" "5445308" "5455390" "5459352" "5542602" "5553769" "5557501" "5561590" "5572404" "5611884" "5651179" "5658831" "5688721" "5720100" "5745344" "5808874" "5819406" "5920125" "5975408" "6000127").PN.	USPAT	2004/05/14 10:53
22	3	5777385.URPN.	USPAT	2004/05/14 10:59
23	7	("4149310" "4561040" "5291064" "5378924" "5525834" "5583073" "5614766").PN.	USPAT	2004/05/14 11:05
26	2	("5592735" "5777385").PN.	USPAT	2004/05/14 11:06
27	1	6162659.URPN.	USPAT	2004/05/14 11:07
28	4074	438/108.ccls. 438/122.ccls. 438/124.ccls. 438/127.ccls. 438/612.ccls. 438/613.ccls. 438/615.ccls.	USPAT; US-PGPUB	2004/05/14 11:15
30	986	(438/108.ccls. 438/122.ccls. 438/124.ccls. 438/127.ccls. 438/612.ccls. 438/613.ccls. 438/615.ccls.) and (bump\$5 ball protrusion solder ubm underbump pad contact) and (heat near (sink spreader dissipat\$6))	USPAT; US-PGPUB	2004/05/14 11:21
31	473	(438/108.ccls. 438/122.ccls. 438/124.ccls. 438/127.ccls. 438/612.ccls. 438/613.ccls. 438/615.ccls.) and (solder adj (bump\$5 ball protrusion)) and (heat near (sink spreader dissipat\$6)) and ((flip ic circuit semiconductor) adj (chip die dice))	USPAT; US-PGPUB	2004/05/14 11:25
33	395	((438/108.ccls. 438/122.ccls. 438/124.ccls. 438/127.ccls. 438/612.ccls. 438/613.ccls. 438/615.ccls.) and (solder adj (bump\$5 ball protrusion)) and (heat near (sink spreader dissipat\$6)) and ((flip ic circuit semiconductor) adj (chip die dice))) and ((substrate carrier module) with (pad contact electrode ubm underbump))	USPAT; US-PGPUB	2004/05/14 12:41
34	175	(solder adj (bump\$5 ball protrusion)) same (heat near (sink spreader dissipat\$6)) same ((flip ic circuit semiconductor) adj (chip die dice)) same ((substrate carrier module) with (pad contact electrode ubm underbump)) same (align\$6 reflow\$6 attach\$6 underfill encapsulat\$6 join\$6 bond\$6)	USPAT; US-PGPUB	2004/05/14 15:06
36	1	6507104.URPN.	USPAT	2004/05/14 14:35
37	13	("5522667" "5619070" "5726079" "5920120" "5939783" "5977626" "6117705" "6150724" "6191360" "6218730" "6255143" "6265771" "6271058").PN.	USPAT	2004/05/14 14:36
35	66	(solder adj (bump\$5 ball protrusion)) and (heat near (sink spreader dissipat\$6)) and ((flip ic circuit semiconductor) adj (chip die dice)) and ((substrate carrier module) with (pad contact electrode ubm underbump)) and (align\$6 reflow\$6 attach\$6 underfill encapsulat\$6 join\$6 bond\$6)	EPO; JPO; DERWENT; IBM_TDB	2004/05/14 14:54
38	19	((bump\$5 ball protrusion) near2 (heat near (sink spreader dissipat\$6))) same ((flip ic circuit semiconductor) adj (chip die dice)) same ((substrate carrier module) with (pad contact electrode ubm underbump)) same (align\$6 reflow\$6 attach\$6 underfill encapsulat\$6 join\$6 bond\$6)	USPAT; US-PGPUB	2004/05/14 15:07
40	390	(bump\$5 ball protrusion) near2 (heat near (sink spreader dissipat\$6))	USPAT; US-PGPUB	2004/05/14 15:09

41	101	((bump\$5 ball protrusion) near2 (heat near (sink spreader dissipat\$6))) and ((flip ic circuit semiconductor) adj (chip die dice)) same ((substrate carrier module) with (pad contact electrode ubm underbump))	USPAT; US-PGPUB	2004/05/14 15:10
43	247	(bump\$5 ball protrusion) near2 (heat near (sink spreader dissipat\$6))	EPO; JPO; DERWENT; IBM_TDB	2004/05/14 15:09
44	19	((bump\$5 ball protrusion) near2 (heat near (sink spreader dissipat\$6))) and ((flip ic circuit semiconductor) adj (chip die dice)) same ((substrate carrier module) with (pad contact electrode ubm underbump))	EPO; JPO; DERWENT; IBM_TDB	2004/05/14 15:10
39	23	((bump\$5 ball protrusion) near2 (heat near (sink spreader dissipat\$6))) same ((flip ic circuit semiconductor) adj (chip die dice)) same ((substrate carrier module) with (pad contact electrode ubm underbump))	USPAT; US-PGPUB	2004/05/14 15:13
42	46	(438/108.ccls. 438/122.ccls. 438/124.ccls. 438/127.ccls. 438/612.ccls. 438/613.ccls. 438/615.ccls.) and ((bump\$5 ball protrusion) near2 (heat near (sink spreader dissipat\$6)))	USPAT; US-PGPUB	2004/05/14 15:17
-	13	5777385.pn. 20020121705.pn. 20020163075.pn. 20020180023.pn. 4034468.pn. 6437240.pn. 6396669.pn. 6495915.pn. 6255143.pn. 6362530.pn. 6479903.pn. 6245186.pn. 6339254.pn.	USPAT; US-PGPUB	2004/05/14 10:28